Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.012”**



**.012”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .004 X .004” Min.**

**Backside Potential: COLLECTOR**

**APPROVED BY: DK DIE SIZE .012” X .012” DATE: 11/11/21**

**MFG: DIONICS THICKNESS .008” P/N: 2N918**

**DG 10.1.2**

#### Rev B, 7/1